

# CALICE

## EUDET Mechanics Meetings

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LAL Orsay

10/2/09

- Some impression from SiW EUDET Demonstrator

## Demonstrator Tests

- Delivery and Quality of PCBs OK

- Gluing of PCBs – Status?

- All boards at hand by the end of last week

- Visit by Cambridge Colleagues

- Successful interconnection

- Baseline for IB/DIF card (space, heat dissipation)

- Cooling System

- Test Program according to Denis and Julien pursued at LAL

- Alveolar Structure for Demonstrator?

- 400 mum Copper Shield and electrical shielding

- Delivered ny 26<sup>th</sup> of January

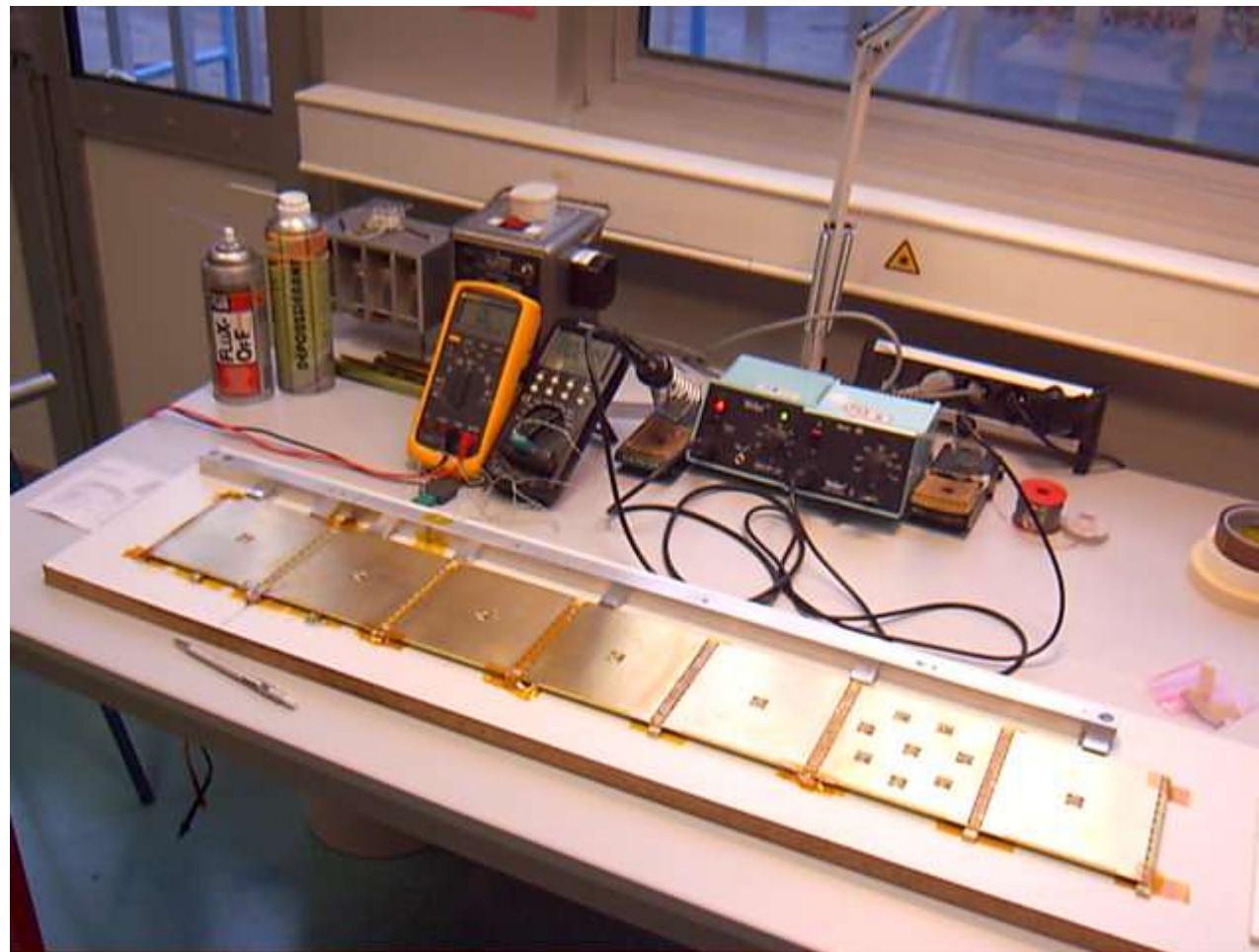
- Small Webpage for the project

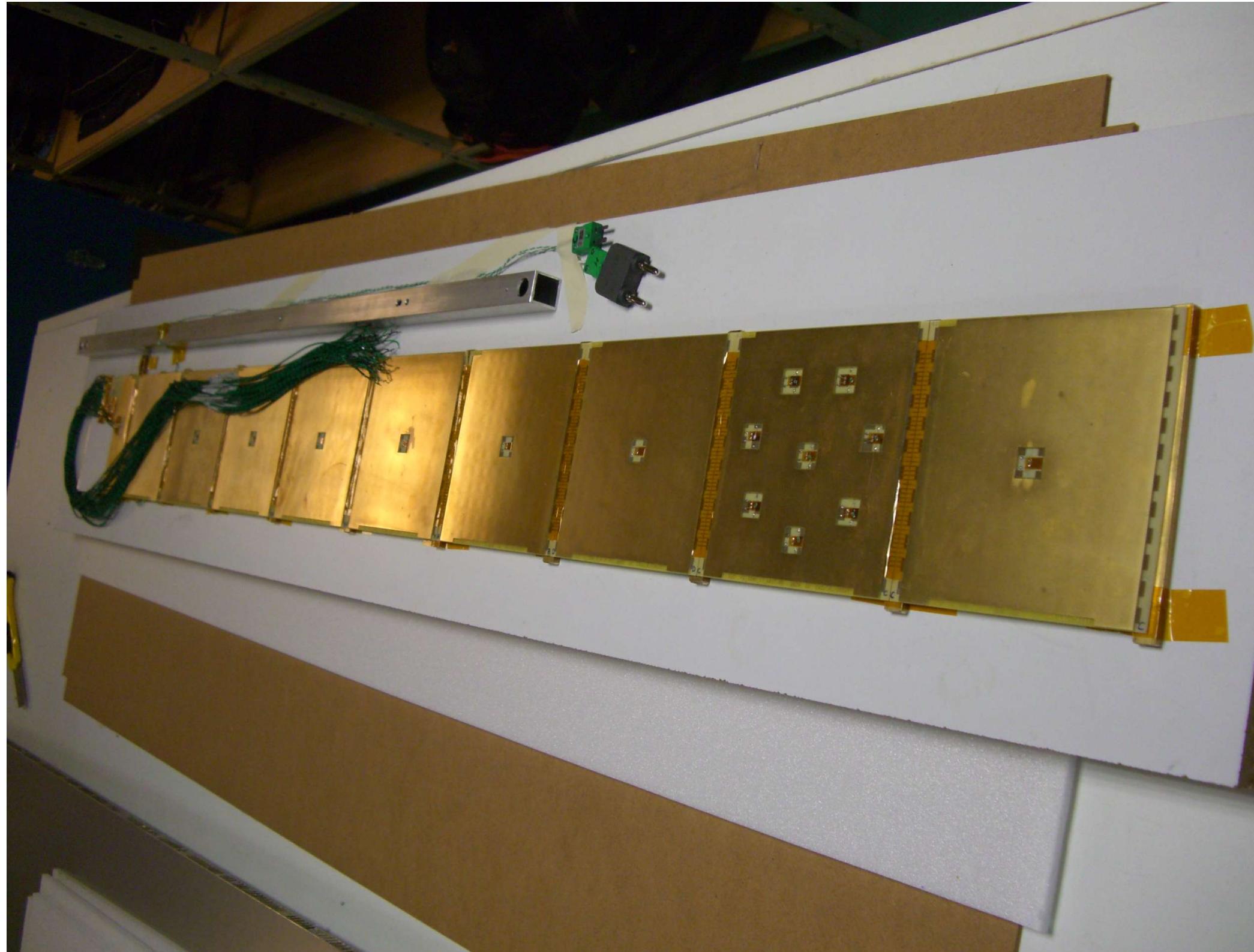
- <http://flc.web.lal.in2p3.fr/poeschl/siwecal.html>

## Workshop with H and Thermal Boards

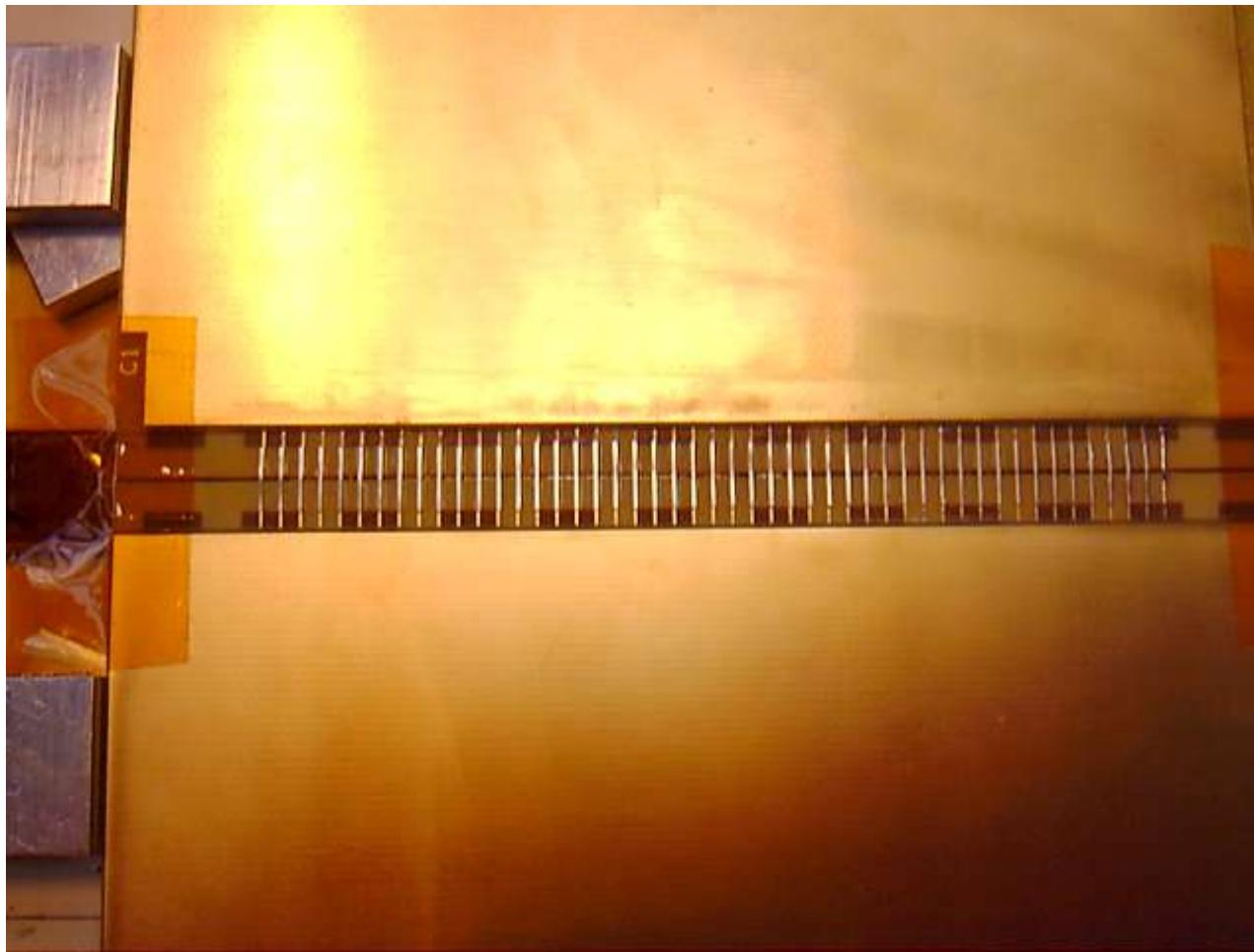


## 7 Boards assembled

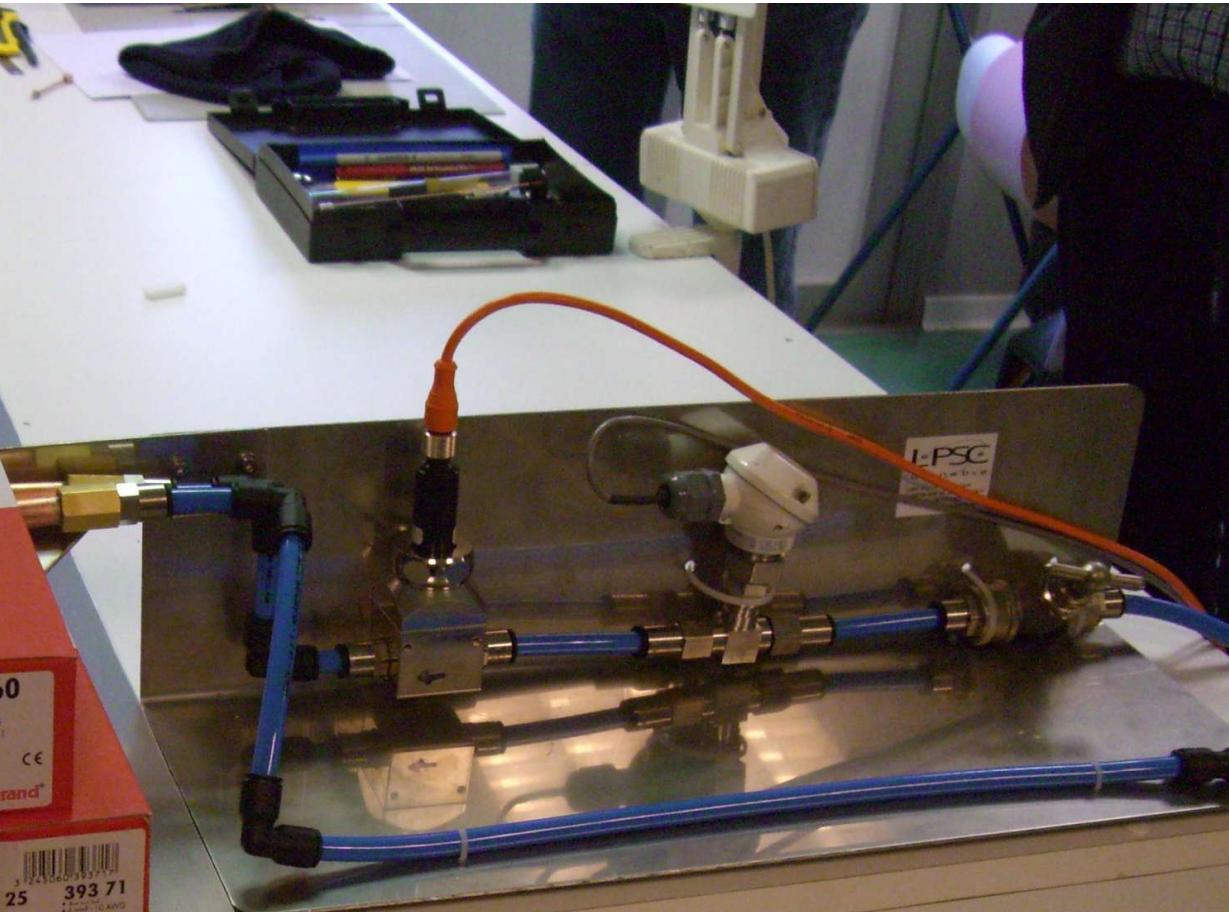




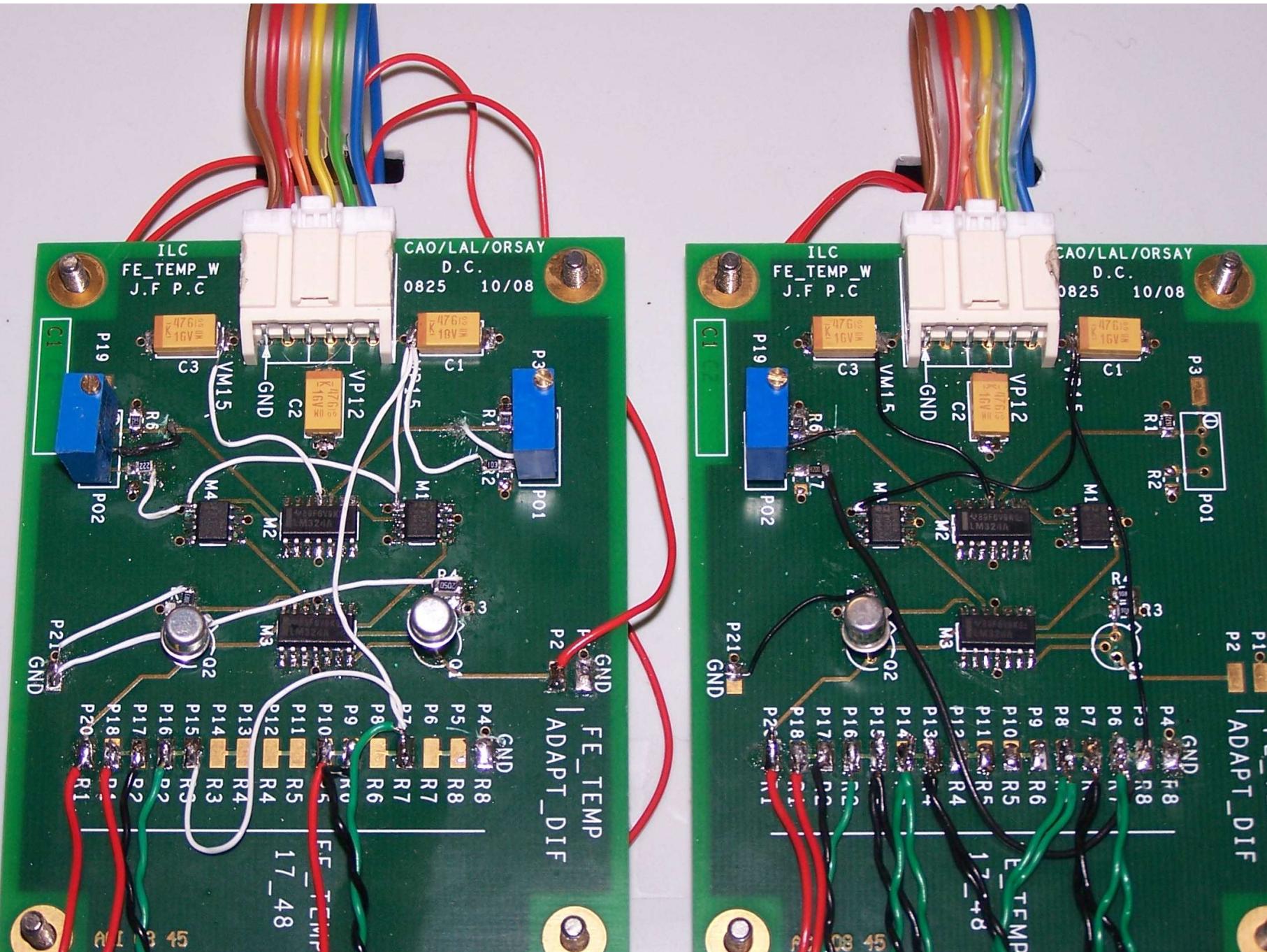
## The joint between two boards



- Joint by halogen lamp heating up tin-bismuth soldering paste  
(Method developed by U. Cambridge)
- Joint realized by P. Cornebise



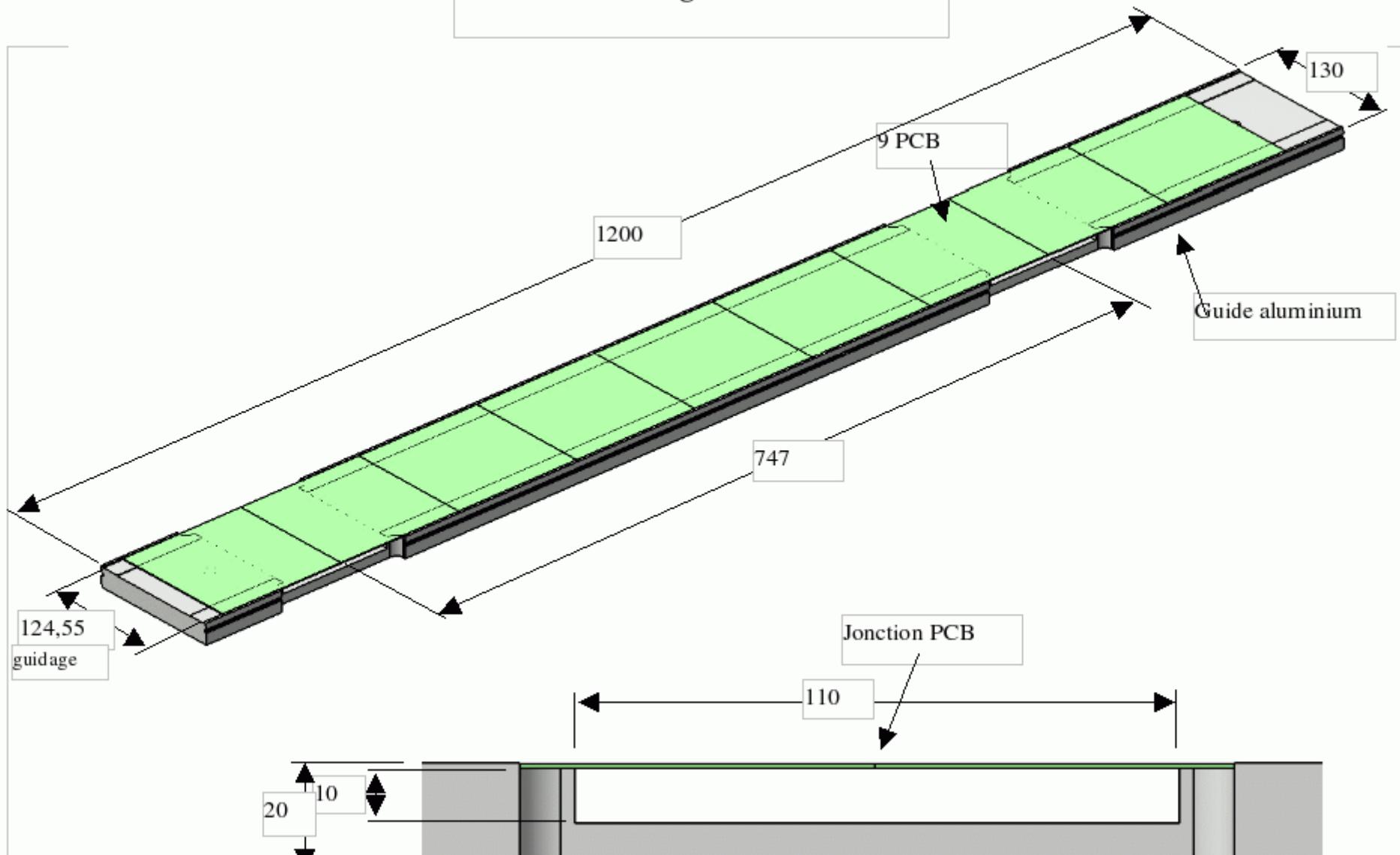




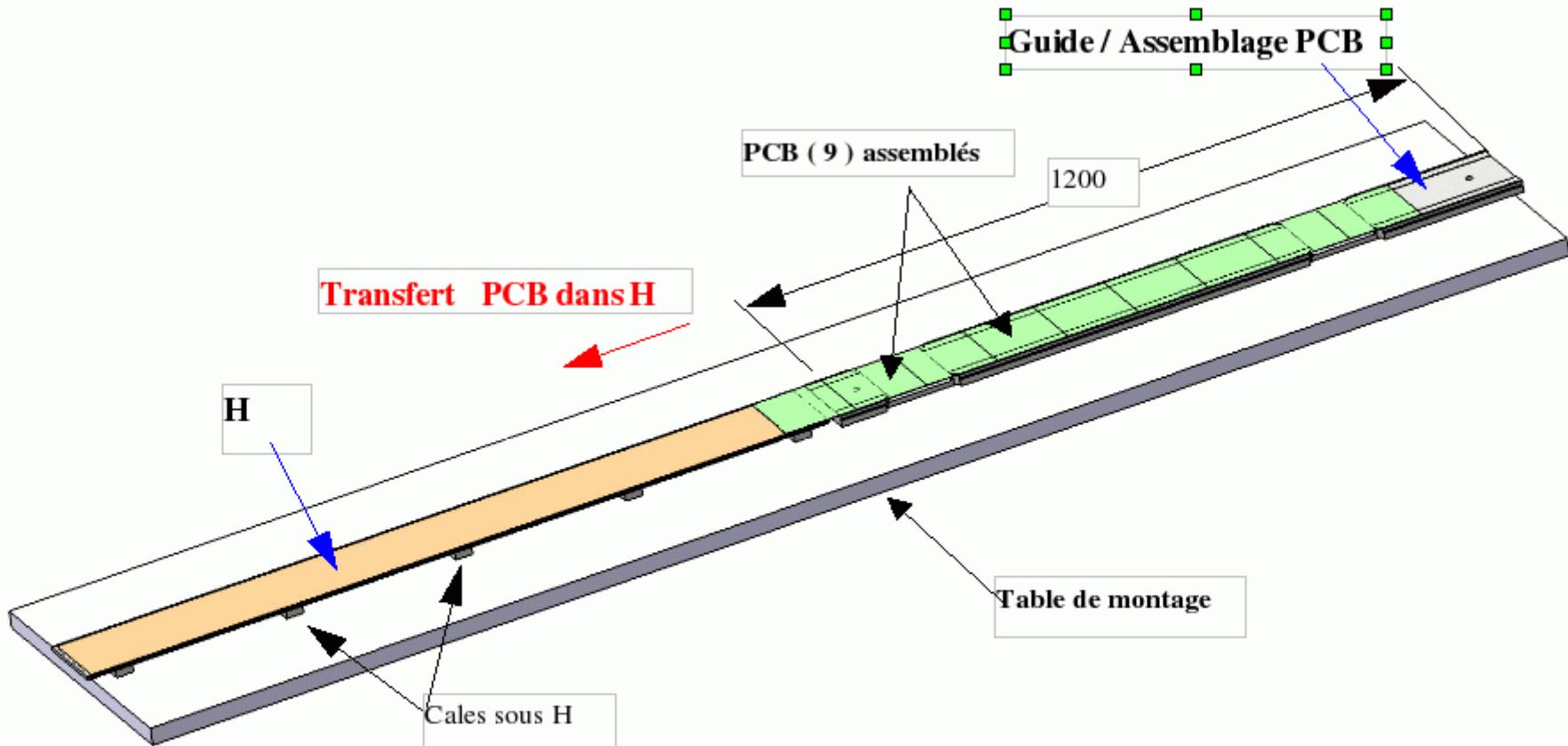


# Integration Cradle

## Guide Assemblage Cartes PCB



## *Transfert PCB / H*



- Forseen to be ready this week
- Will be used for second thermal layer



## Next steps

- Analysis of First round of thermal tests
- Compilation of a second layer with thermal drain and electrical shielding  
to be noted thermal drain and copper shielding delivered by Aboud end of Jan.
- Thermal tests ~10<sup>th</sup> of March  
Smaller heat dissipation (0.317 – 0.215 W)
- Insertion of Slab into alveolar structure

## Agenda for the calice meeting

- 1) R. Poeschl: Outlook on 2009 (5 Min.)
- 2) R. Poeschl: EUDET Module - From the TDR to the demonstrator (15. Min)
- 3) R. Poeschl for Marc Anduze (15 Min.): Mechanical structures
- 4) D. Grondin or J. Giraud: First Results from Thermal Tests with the demonstrator (20 Min.)
- 5) R. Cornat: News on SiW Wafers 15. Min.
- 6) S. Callier: SiW Ecal Electronics – SKIROC and FEV7 (to be shared with Corean Groups) 25 Min.
- 7) D. Jeans: DAQ for the Ecal 10 Min.
- 8) R. Poeschl (from Analysis meeting): PCB Irradiation Tests 15 Min.

Makes up 2 h